



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Applicant(s): Sung Dae Cho
Assignee: Samsung Electronics Co., Ltd.
Title: Reel-Deployed Printed Circuit Board And Method For Manufacturing Chip-On-Board Packages
Serial No.: 09/827,112 Filing Date: April 5, 2001
Examiner: J. Alcala Group Art Unit: 2841
Docket No.: AB-698-1D US

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San Jose, California
October 22, 2001

COMMISSIONER FOR PATENTS
Washington, D. C. 20231

RESPONSE TO RESTRICTION REQUIREMENT

Dear Sir:

This is a response to the Office Action dated September 21, 2001 which has statutorily shortened period for response that ends October 22, 2001. Please amend the above-identified patent application as follows.

IN THE CLAIMS

The following is a clean version of the entire set of pending claims. In accordance with CFR § 1.121(c)(1)(ii), Attachment A provides a marked up version of the claims containing the newly introduced changes.

B1

1. (Amended) A reel-deployable printed circuit board comprising:
an elongated, flexible base board having opposite edges and a slit formed into it, the slit having an inner periphery defining a unit board within the flexible base board; and,
at least a connection bar connecting the unit board to the base board such that the unit board is pivotable on the connection bar relative to the base board.

2. The circuit board of Claim 1, further comprising:
a bonding pad on a top surface of the unit board;
a contact on a bottom surface of the unit board; and,
a via hole through the unit board electrically connecting the bonding pad to the contact.

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